

■ Features

- High isolation 5000 VRMS
- DC input with random-phase photo triac output
- Operating temperature range - 40 °C to 110 °C
- RoHS & REACH Compliance
- Halogen free
- MSL class 1
- Regulatory Approvals
 - UL - UL1577
 - VDE - EN60747-5-5(VDE0884-5)
 - CQC – GB4943.1, GB8898

■ Description

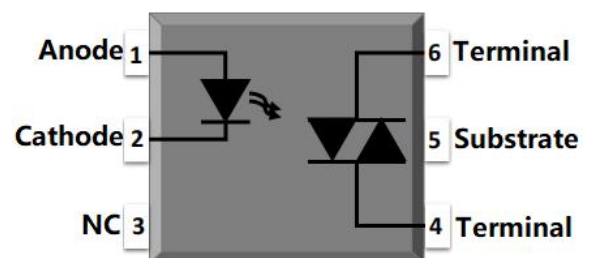
The MPC301X, MPC302X and MPC305X series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo triac in a plastic DIP6 package with different lead forming options.

With the robust coplanar double mold structure, MPC301X, MPC302X and MPC305X series provide the most stable isolation feature.

■ Applications

- Solenoid/valve controls
- Lighting controls
- Motor controls
- Temperature controls
- Static AC power switches
- Solid state relays
- Interfacing microprocessors to 115 to 240VAC peripherals

■ Schematic





MPC301X, MPC302X, MPC305X Series
DIP6, DC Input, Random-Phase Photo TRIAC Coupler

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	VALUE	UNIT	NOTE
INPUT				
Forward Current	I_F	60	mA	
Reverse Voltage	V_R	6	V	
Junction Temperature	T_j	125	°C	
Input Power Dissipation	P_i	100	mW	
OUTPUT				
Off-state Output Terminal Voltage	MPC301X	V_{DRM}	250	V
	MPC302X		400	
	MPC305X		600	
Peak Repetitive Surge Current PW=100μs, 120pps	I_{TSM}	1	A	
On-State RMS Current	$I_{T(RMS)}$	100	mA	
Junction Temperature	T_j	125	°C	
Output Power Dissipation	P_o	300	mW	
COMMON				
Total Power Dissipation	P_{tot}	400	mW	
Isolation Voltage	V_{iso}	5000	V _{rms}	1
Operating Temperature	T_{opr}	-40~100	°C	
Storage Temperature	T_{stg}	-55~125	°C	
Soldering Temperature	T_{sol}	260	°C	2

Note 1. AC For 1 Minute, R.H. = 40 ~ 60%

Note 2. For 10 seconds



MPC301X, MPC302X, MPC305X Series
DIP6, DC Input, Random-Phase Photo TRIAC Coupler

ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C							
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION	NOTE
INPUT							
Forward Voltage	V _F	-	1.24	1.4	V	I _F =10mA	
Reverse Current	I _R	-	-	10	μA	V _R =6V	
Input Capacitance	C _{in}	-	8.5	250	pF	V=0, f=1kHz	
OUTPUT							
Peak Off-state Current, Either Direction	I _{DRM}	-	-	100	nA	V _{DRM} =Rated V _{DRM} I _F =0	3
Peak On-state Current, Either Direction	V _{TM}	-	1.58	2.5	V	I _{TM} =100mA	
Critical Rate of Rise of Off-state Voltage	dV/dt	1000	-	-	V	V _{PEAK} =Rated V _{DRM}	4
TRANSFER CHARACTERISTICS							
LED Trigger Current	MPC3010, MPC3021, MPC3051	I _{FT}	-	-	15	mA	Terminal Voltage = 3V I _{TM} =100mA
	MPC3011, MPC3022, MPC3052,		-	-	10		
	MPC3012, MPC3023, MPC3053,		-	-	5		
Holding Current Saturation Voltage	I _H	-	257	-	μA		
Isolation Resistance	R _{iso}	10 ¹²	10 ¹⁴	-	Ω	DC500V, 40 ~ 60% R.H.	
Floating Capacitance	C _{io}	-	0.8	-	pF	V=0, f=1MHz	

Note3. Test voltage must be applied within dV/dt rating.

Note4. Refer to Fig.15 & Fig.16.

CHARACTERISTIC CURVES

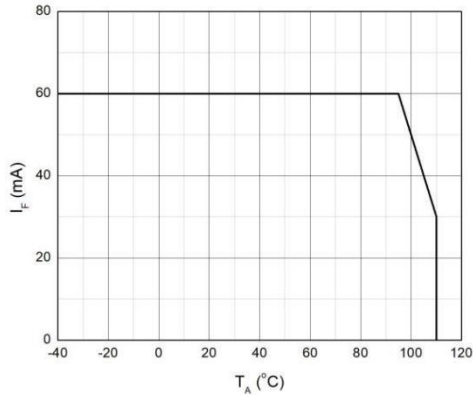


Fig.1 Forward Current vs. Ambient Temperature

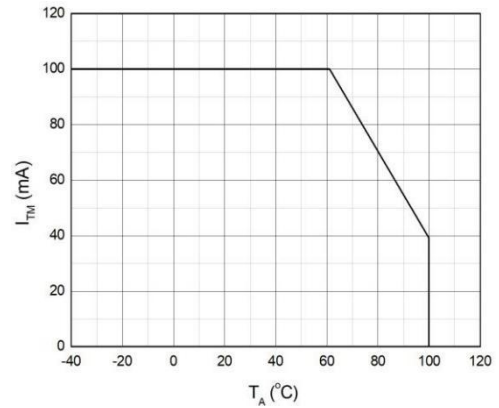


Fig.2 On-state Terminal Current vs. Ambient Temperature

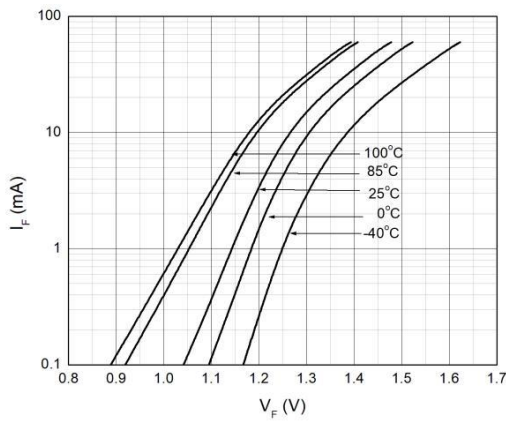


Fig.3 Forward Current vs. Forward Voltage

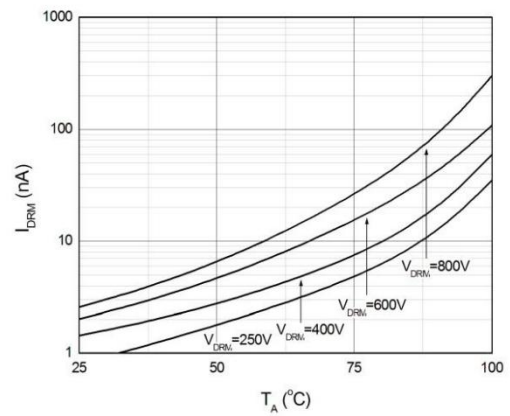


Fig.4 Off-state Terminal Current vs. Ambient Temperature

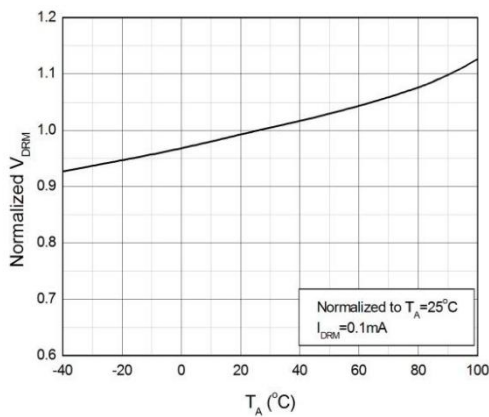


Fig.5 Normalized Off-state Terminal Voltage vs. Ambient Temperature

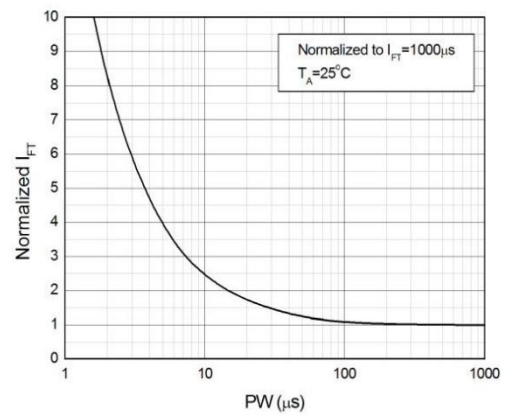


Fig.6 Normalized Trigger Current vs. LED Trigger Pulse Width

CHARACTERISTIC CURVES

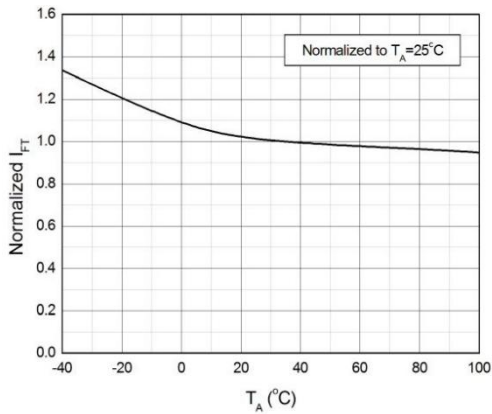


Fig.7 Normalized Trigger Current vs. Ambient Temperature

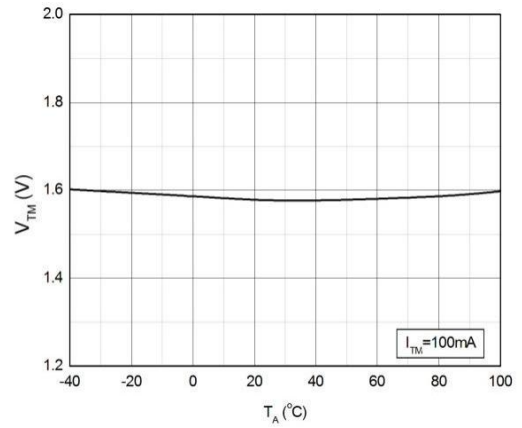


Fig.8 On-state Terminal Voltage vs. Ambient Temperature

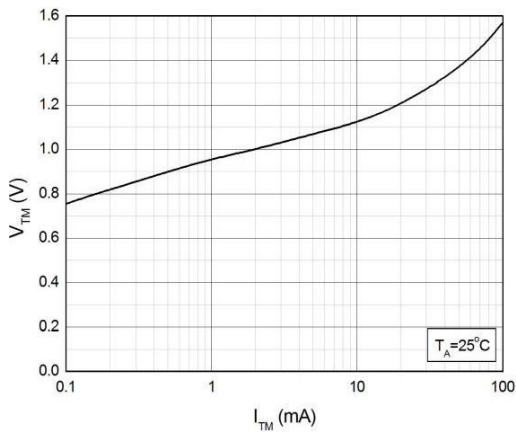


Fig.9 On-state Terminal Voltage vs. On-state Terminal Current

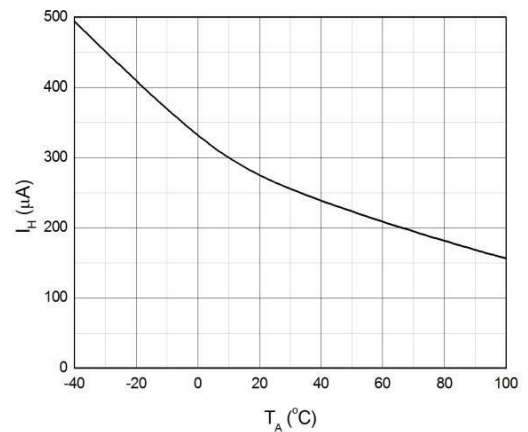


Fig.10 Holding Current vs. Ambient Temperature

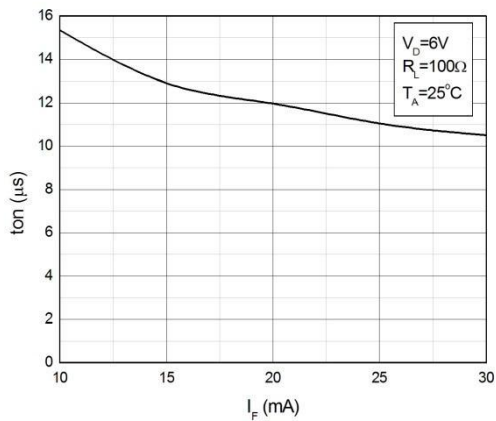


Fig.11 Turn On Time vs. Forward Current

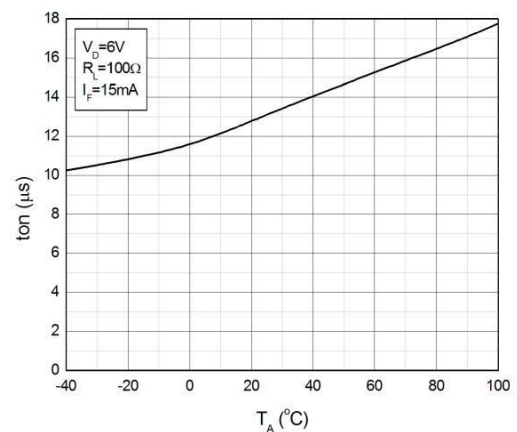


Fig.12 Turn On Time vs. Ambient Temperature

TEST CIRCUITS

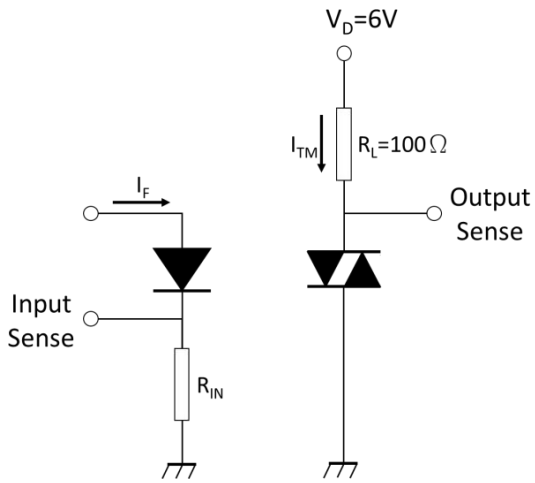


Fig.13 Test Circuits of Turn On Time

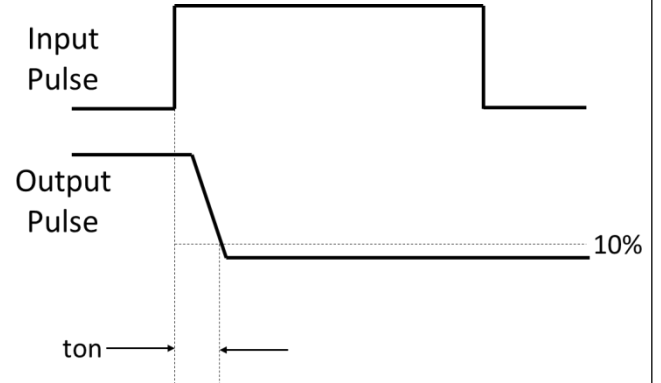


Fig.14 Waveforms of Turn On Time

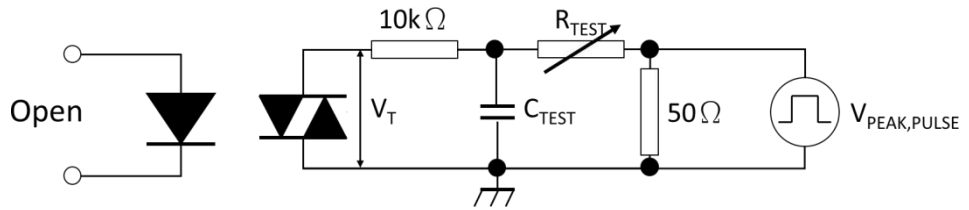


Fig.15 Test Circuits of dV/dt

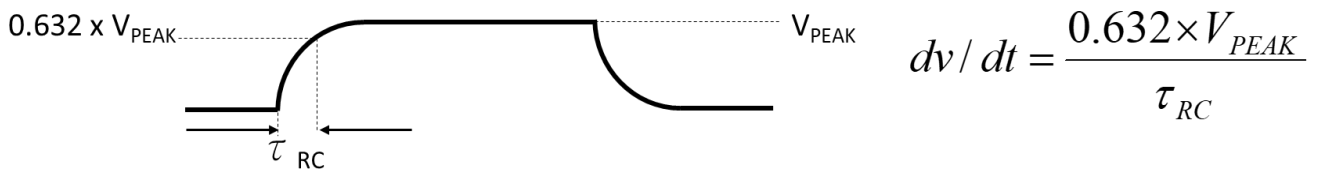
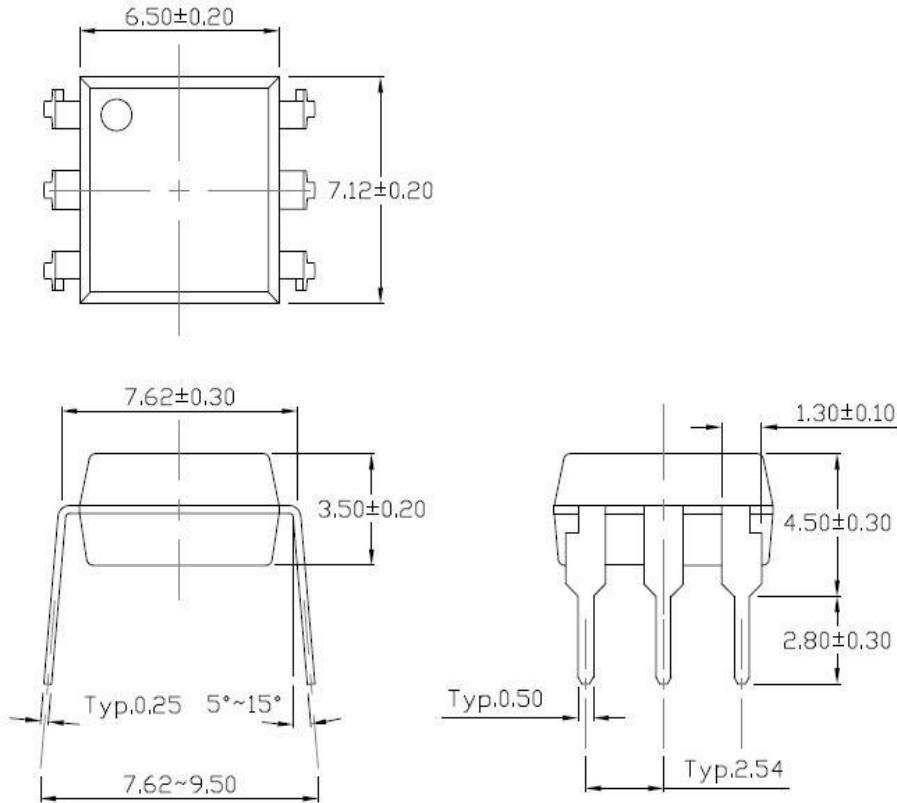


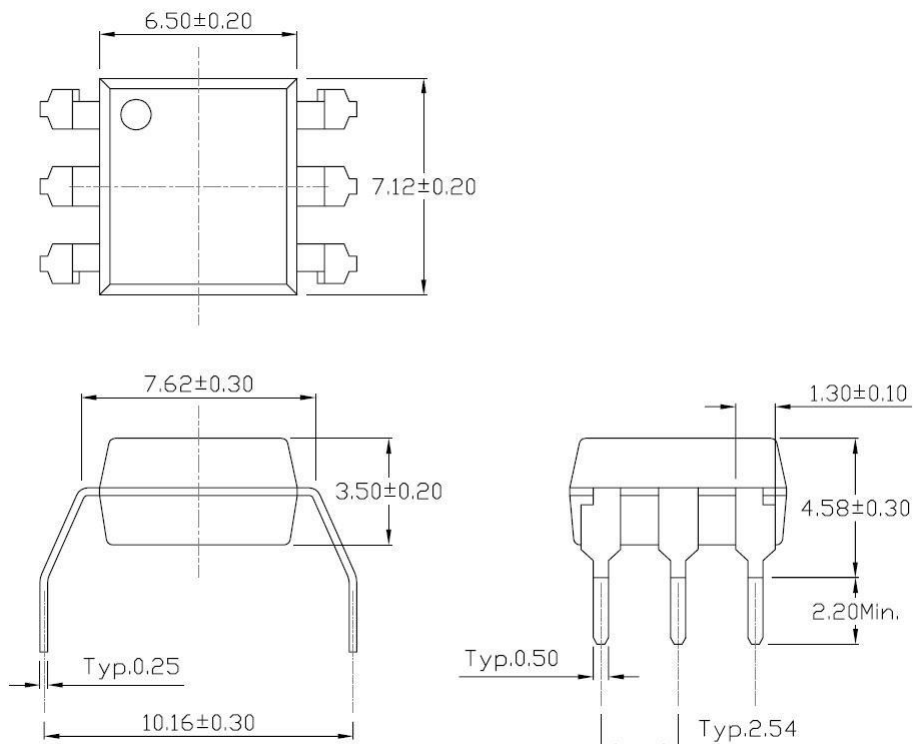
Fig.16 Waveforms of dV/dt

PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

Standard DIP-Through Hole(DIP Type)

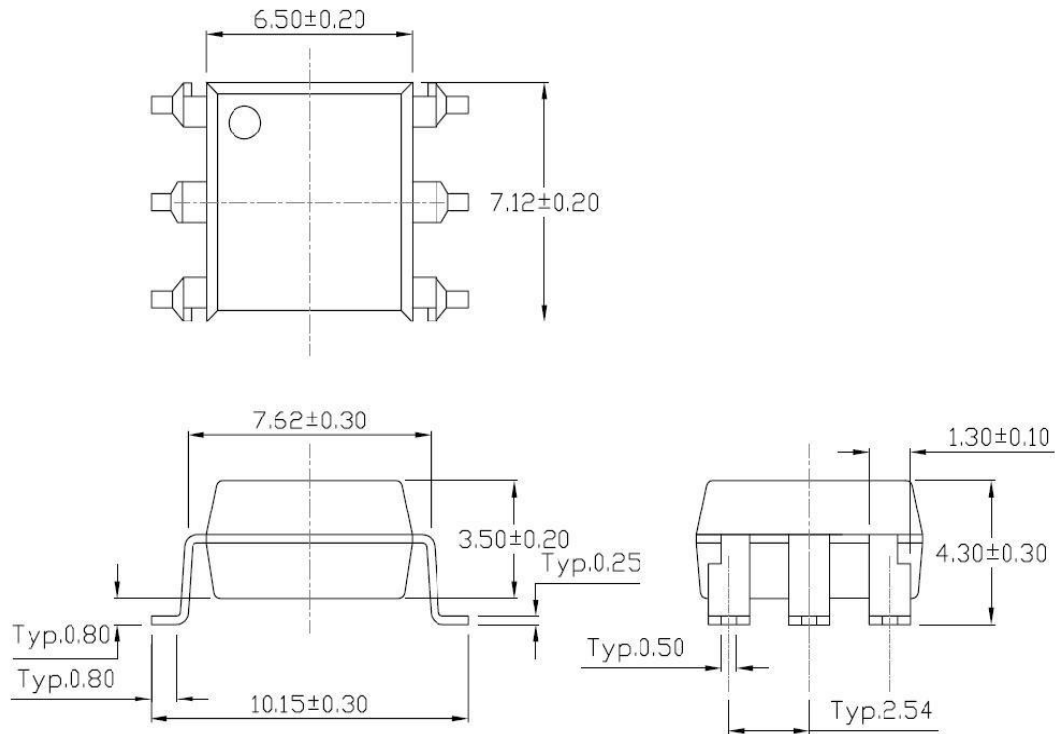


Gullwing(400mil) Lead Forming-Through Hole(M Type)

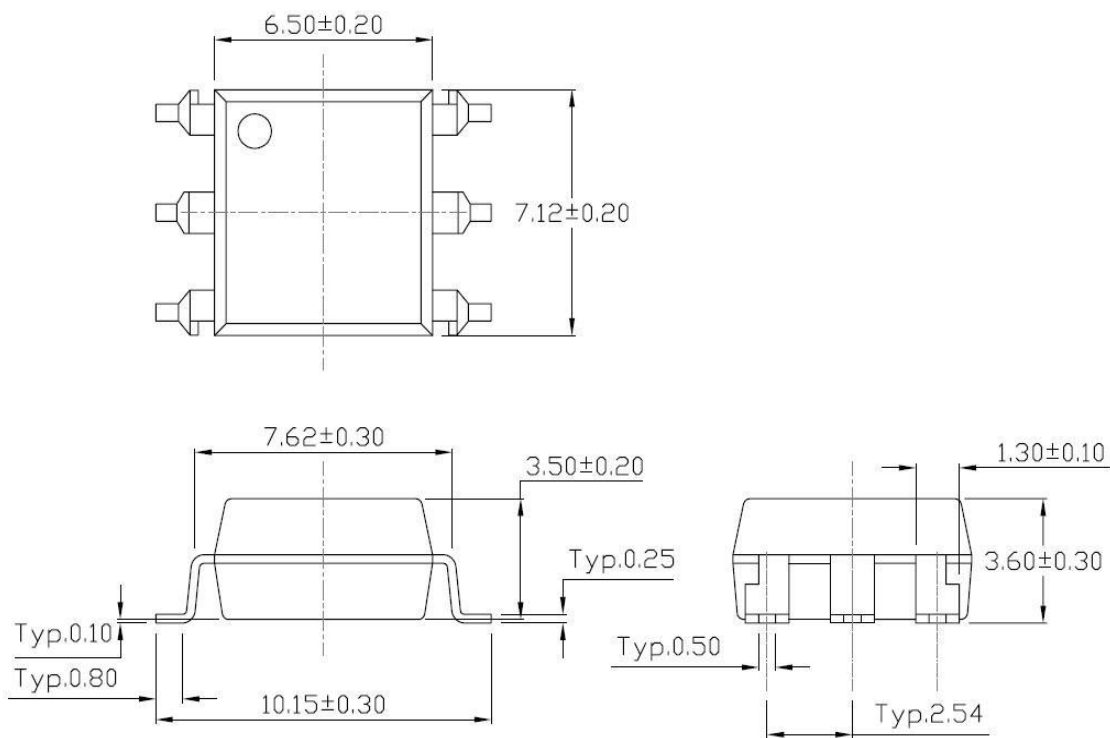


PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

Surface Mount Lead Forming(S Type)

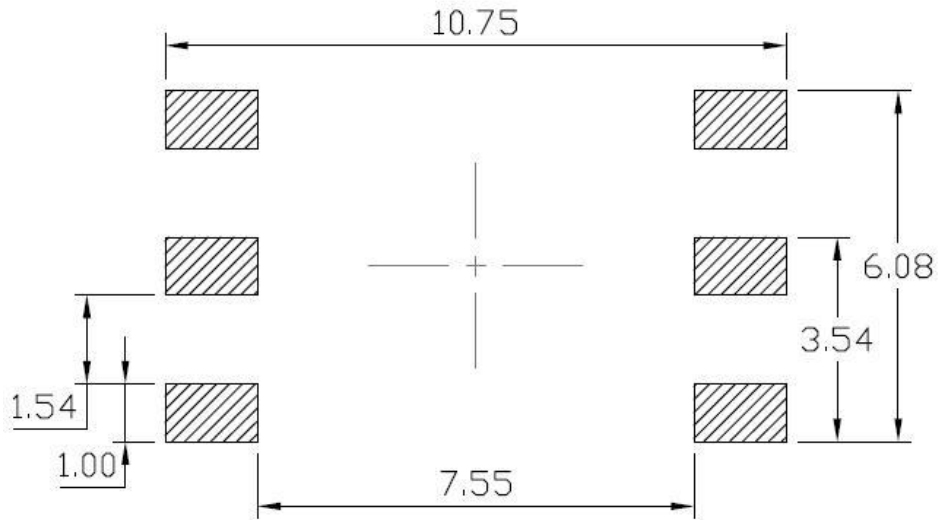


Surface Mount(Low Profile) Lead Forming(SL Type)

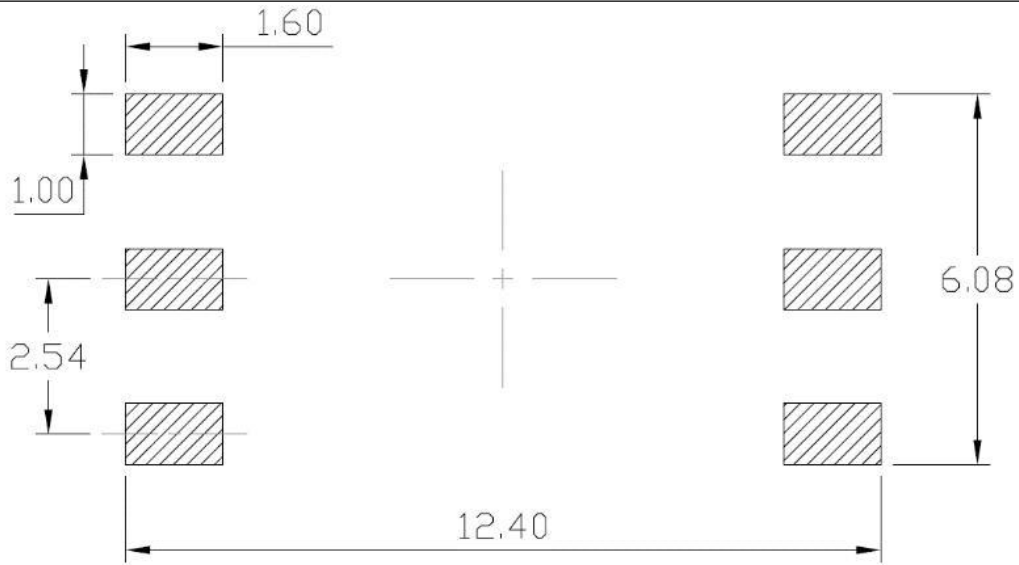


RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

Surface Mount Lead Forming & Surface Mount(Low Profile) Lead Forming

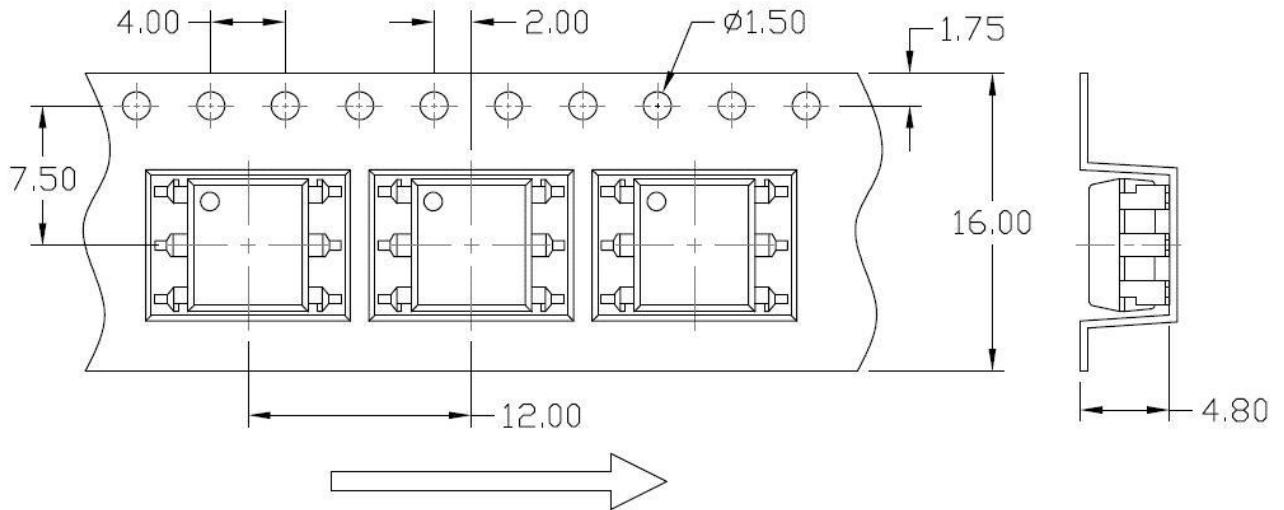


Surface Mount(Gullwing) Lead Forming

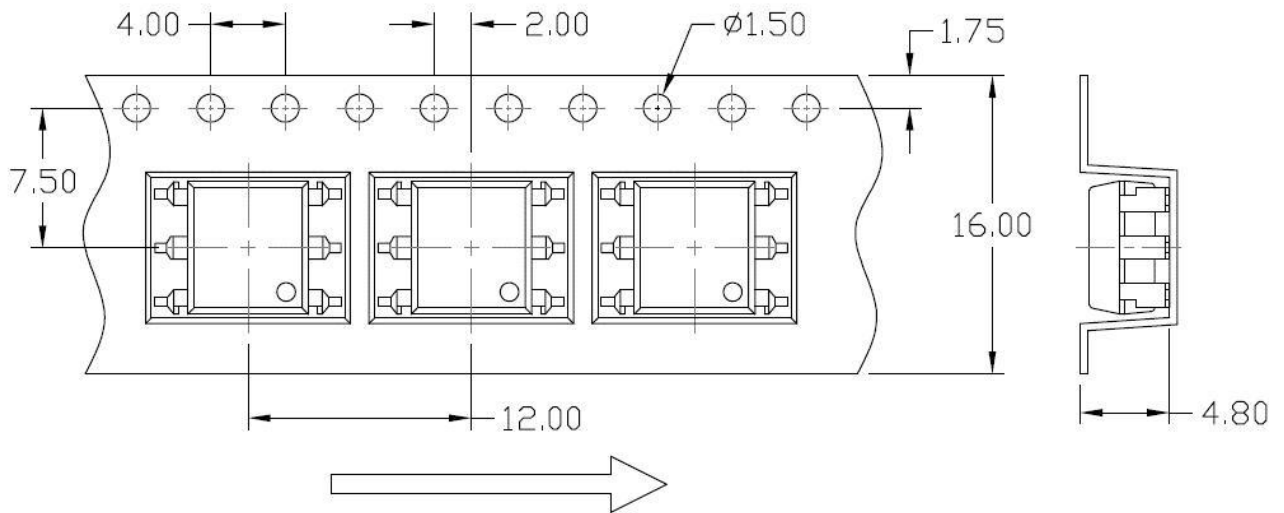


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S(T1) & SL(T1)

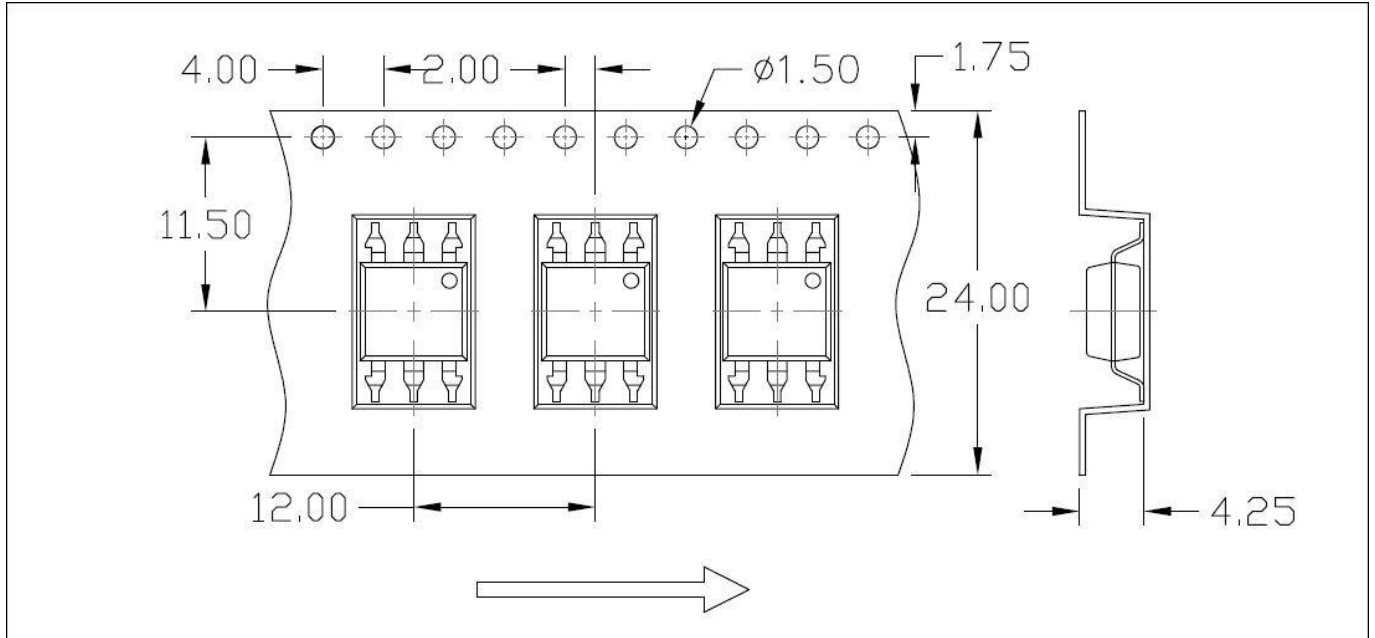


Option S(T2) & SL(T2)

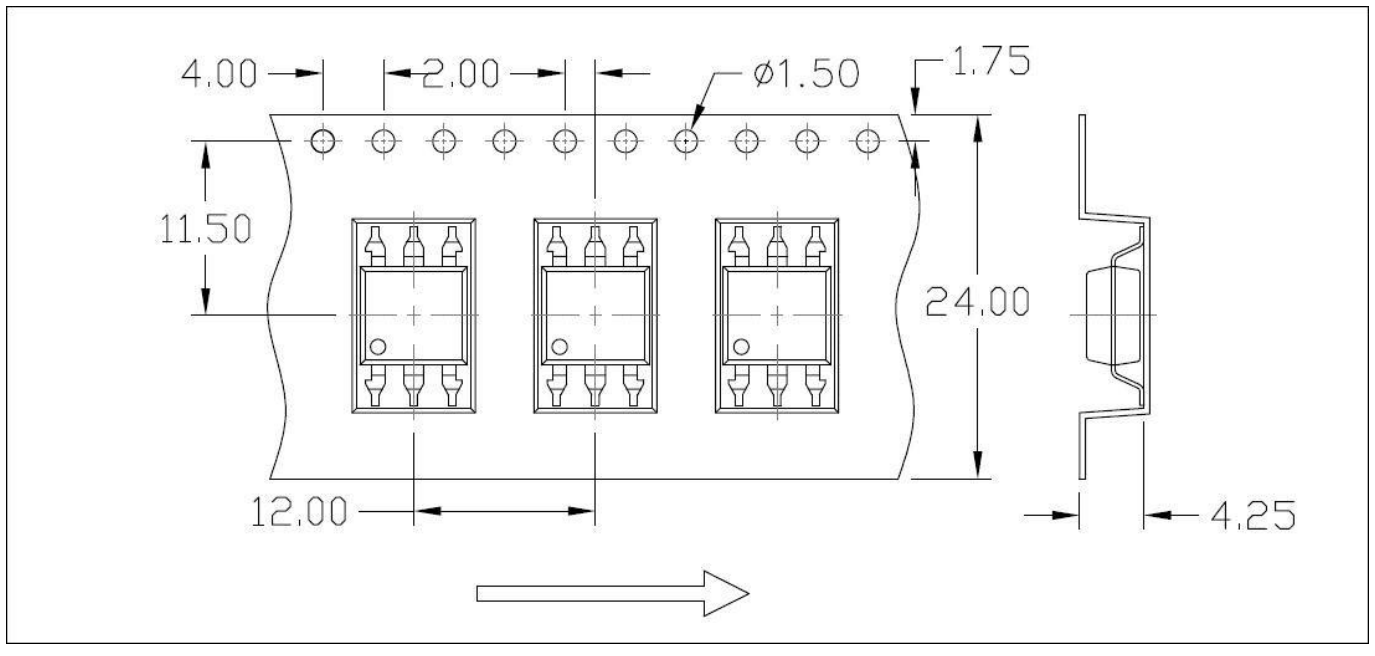


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option SLM(T1)

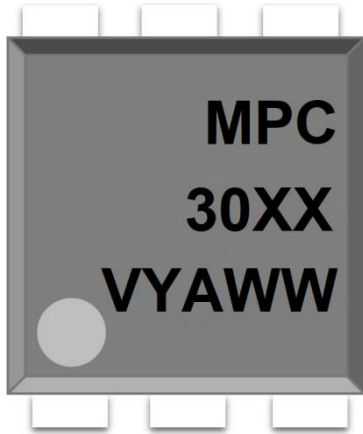


Option SLM(T2)



ORDERING AND MARKING INFORMATION

MARKING INFORMATION



MPC : Company Abbr.
30XX : Part Number&Rank
V : VDE Option
Y : Fiscal Year
A : Manufacturing Code
WW : Work Week

ORDERING INFORMATION

MPC30XX(Y)(Z)-GV

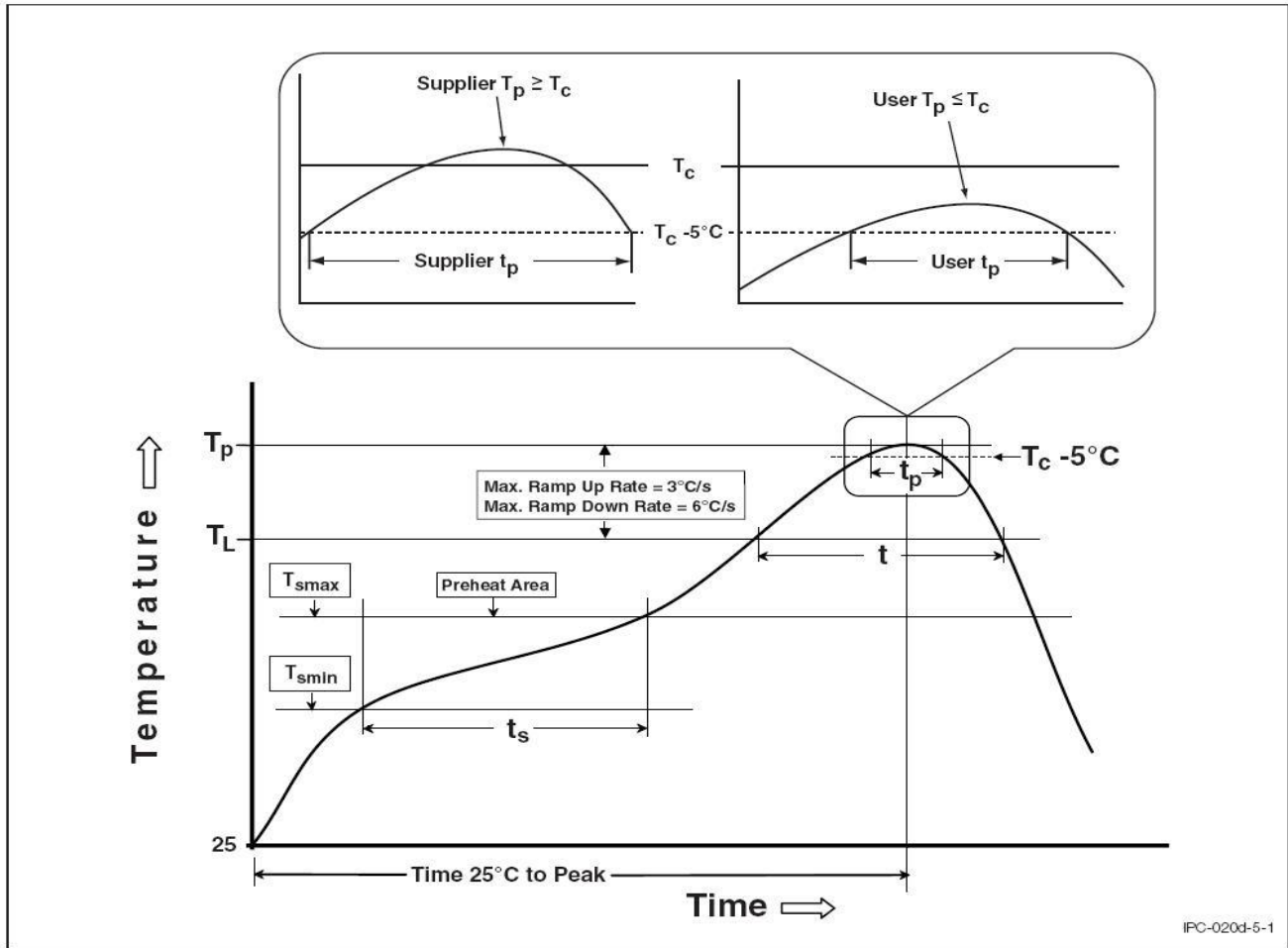
MPC – Company Abbr.
 30XX – Part Number&Rank (10/11/12/21/22/23/51/52/53)
 Y – Lead Form Option (M/S/SL/None)
 Z – Tape and Reel Option (T1/T2)
 G – Material Option (G: Green, None: Non-Green)
 V – VDE Option (V or None)

PACKING QUANTITY

Option	Quantity	Quantity – Inner box	Quantity – Outer box
None	50 Units/Tube	32 Tubes/Inner box	10 Inner box/Outer box = 16k Units
M	50 Units/Tube	32 Tubes/Inner box	10 Inner box/Outer box = 16k Units
S(T1)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units
S(T2)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units
SL(T1)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units
SL(T2)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units

REFLOW INFORMATION

REFLOW PROFILE



IPC-0203-5-1

Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	100	150°C
Temperature Max. (T _{smax})	150	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.	3°C/second max.
Liquidous Temperature (T _L)	183°C	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



DISCLAIMER

- Our company is continually improving the quality, reliability, function and design. Our company reserves the right to make changes without further notices.
- The characteristic curves shown in this datasheet are representing typical performance which are not guaranteed.
- This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or lifesaving applications or any other application which can result in human injury or death.
- Immerge unit's body in solder paste is not recommended.
- Discoloration might be occurred on the package surface after soldering, reflow or long-time use. It neither impacts the performance nor reliability.

■ Revision History

Version	Date	Subjects (major changes since last revision)
1.0	2022-07-21	Datasheet Complete